Please rewrite paragraph [0057] as follows:

[0057] (ii) Production of photosensitive resin plates 1 - 17:

Each of the above-described water-soluble photosensitive resin compositions 1-17 was coated onto a polyester film (cover film), followed by drying to form a photosensitive layer of 0.7 mm in thickness. Then, a base was adhered thereto to provide photosensitive resin plates (raw plates or to-be-exposed plates) 1 - 17 each.

Please rewrite paragraph [0058] as follows:

[0058] (iii) Evaluation of Depth of Non-printing area:

After each of the cover film was released from the photosensitive resin plates 1 - 17, the photosensitive resin plates 1 - 17 were exposed through a mask having independent fine lines of 150 μ m, using a chemical lamp of 20 W from a distance of 45 mm for 10 minutes, and then, the unexposed areas were removed by washing out with water of 35°C using a brush, followed by drying at 80°C for 5 minutes to make printing plates.

[Please rewrite paragraph [0060] as follows: [0060] EXAMPLES 18-34:

By following the same procedures as Examples 1 - 17 above, except that o-toluenesulfonamide was used instead of p-toluenesulfonamide, water-soluble photosensitive resin compositions 18 - 34 were prepared, and photosensitive resin plates 18 - 34 were obtained.

Please rewrite paragraph [0061] as follows:

[0061] Using the plates 18 - 34, the depth was evaluated in the same manner as described in Examples 1 - 17 above. The results are shown in Table I.

Please replace Table I on page 23 of the specification, submitted with the response dated March 7, 2002, with Table I submitted herewith on a separate sheet.